

NOTES: UNLESS OTHERWISE SPECIFIED.
1. FABRICATE PER IPC-6012A CLASS 2.

DIELECTRIC: FR4_ITEQ IT168G.
COPPER: AS PER STACKUP.

U.L. RATING: 94V-0 MINIMUM

3. SURFACE FINISH: ENIG

4. SOLDER MASK MATERIAL SHALL MEET ALL THE REQUIREMENTS OF IPC-SM-840C AND SHALL BE GREEN IN COLOR AND APPLIED OVER BARE COPPER.
5. SILK SCREEN LEGEND TO BE APPLIED PER LAYER STACKUP USING WHITE NON-CONDUCTIVE EPOXY INK.

6. 100% CONTINUITY TESTING USING DATABASE NETLIST SHALL BE PERFORMED. VENDOR TO IDENTIFY TEST PASSED IN SECONDARY SIDE.

7. VENDOR TO MARK DATE CODE AND LOGO IN ETCH OR IN LEGEND.

8. BOW AND TWIST SHALL NOT EXCEED 0.7% OF LONGEST SIDE.

9. DIELECTRICS AND LINewidthS MAY BE ADJUSTED TO MEET THE IMPEDANCE REQUIREMENTS.

10. MINIMUM CONDUCTOR WIDTH: 4.0 MILS

MINIMUM SPACING: 3.8 MILS

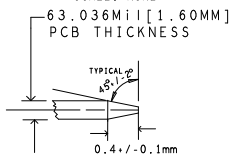
11. THE PCB EDGE NEAR AMC CONNECTOR EDGE SHOULD BE AS SHOWN IN THE BELOW FIG.

12. THE ALL DIMENSIONS ARE IN "MM [INCHES]".

NOTE: 'Inner layer non-functional via pads must be removed from all serdes vias and RTM connector pins'.

SCORE DETAIL

SCALE: NONE



LAYER STACK-UP

PRIMARY SIDE, SILK SCREEN	- 2 MILS
PRIMARY SIDE, SOLDER MASK	- 1.794 MILS
PRIMARY SIDE, LAYER 1	- 3.596 MILS
DIELECTRIC	- 1.26 MILS
GROUND LAYER, LAYER 2	- 4 MILS
DIELECTRIC	- 1.26 MILS
INNER LAYER, LAYER 3	- 5.014 MILS
DIELECTRIC	- 1.26 MILS
POWER LAYER, LAYER 4	- 5 MILS
DIELECTRIC	- 1.26 MILS
INNER LAYER, LAYER 5	- 3.814 MILS
DIELECTRIC	- 1.26 MILS
GROUND LAYER, LAYER 6	- 4 MILS
DIELECTRIC	- 1.26 MILS
GROUND LAYER, LAYER 7	- 3.814 MILS
DIELECTRIC	- 1.26 MILS
INNER LAYER, LAYER 8	- 5 MILS
DIELECTRIC	- 1.26 MILS
POWER LAYER, LAYER 9	- 5.014 MILS
DIELECTRIC	- 1.26 MILS
INNER LAYER, LAYER 10	- 4 MILS
DIELECTRIC	- 1.26 MILS
GROUND LAYER, LAYER 11	- 3.596 MILS
DIELECTRIC	- 1.794 MILS
SECONDARY SIDE, SOLDER MASK	- 2 MILS
SECONDARY SIDE, SILK SCREEN	- 2 MILS

63.036 MILS +/-10%

SINGLE ENDED

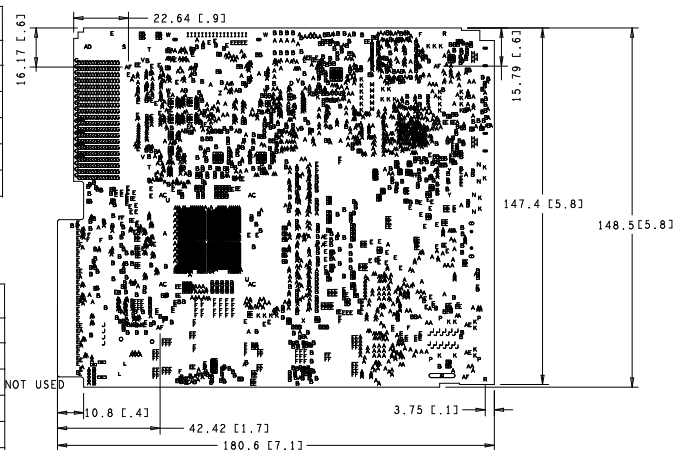
LAYER NO.	CONDUCTOR WIDTH	REFERENCE LAYER	IMPEDANCE +/-10%
L01_TOP	6 MILS	L02_GND1	50 OHMS
L03_SIG1	4 MILS	L02_GND1	50 OHMS
L05_SIG2	4.2 MILS	L06_GND2	50 OHMS
L08_SIG3	4.2 MILS	L07_GND3	50 OHMS
L10_SIG4	4.2 MILS	L11_GND4	50 OHMS
L12_BOT	6 MILS	L11_GND4	50 OHMS

DIFFERENTIAL 100E

LAYER NO.	CONDUCTOR WIDTH	SPACING	REFERENCE LAYER	IMPEDANCE +/-10%
L01_TOP	4 MILS	6 MILS	L02_GND1	100 OHMS
L03_SIG1	4 MILS	7.5 MILS	L02_GND1	100 OHMS
L05_SIG2	4 MILS	7.5 MILS	L06_GND2	100 OHMS
L08_SIG3	4 MILS	7.5 MILS	L07_GND3	100 OHMS
L10_SIG4	4 MILS	7.5 MILS	L11_GND4	100 OHMS
L12_BOT	4 MILS	6 MILS	L11_GND4	100 OHMS

DIFFERENTIAL 90E

LAYER NO.	CONDUCTOR WIDTH	SPACING	REFERENCE LAYER	IMPEDANCE +/-10%
L01_TOP	4.5 MILS	4.5 MILS	L02_GND1	90 OHMS
L03_SIG1	4 MILS	4.5 MILS	L02_GND1	90 OHMS
L10_SIG4	4 MILS	4.5 MILS	L11_GND4	90 OHMS
L12_BOT	4.5 MILS	4.5 MILS	L11_GND4	90 OHMS



NOT USED

NOT USED

COMPANY NAME : eINFOCHIPS LIMITED
DATE: 04-11-2014 JOB NUMBER: EINF4982C
DESIGNED AT: eINFOCHIPS LIMITED
PART NO/CARD REF: K2E EVM CARD REV: 03
FILM LAYER: FABRICATION LAYER



CAUTION
SENSITIVE ELECTRONIC DEVICES-CLASS 1

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
-	INITIAL RELEASE	04/11/2014	Library
1	CHANGES IN FAB DETAILS & IMPEDANCE DETAILS	04/11/2014	QA & CAM

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	SIZE	TOLERANCE	PLATED	QTY
A	8.0	+3.0/-3.0	PLATED	2653
B	10.0	+3.0/-3.0	PLATED	930
C	11.81	+3.0/-3.0	PLATED	55
D	12.0	+3.0/-3.0	PLATED	89
E	14.0	+3.0/-3.0	PLATED	303
F	16.0	+3.0/-3.0	PLATED	131
G	18.0	+3.0/-3.0	PLATED	320
H	28.0	+3.0/-3.0	PLATED	10
I	32.0	+3.0/-3.0	PLATED	17
J	35.43	+3.0/-3.0	PLATED	24
K	40.0	+3.0/-3.0	PLATED	39
L	42.0	+3.0/-3.0	PLATED	2
M	45.0	+3.0/-3.0	PLATED	5
N	51.0	+3.0/-3.0	PLATED	4
O	53.0	+3.0/-3.0	PLATED	2
P	61.81	+3.0/-3.0	PLATED	4
Q	106.0	+3.0/-3.0	PLATED	2
R	125.0	+3.0/-3.0	PLATED	1
T	156.0	+3.0/-3.0	PLATED	2
U	26.0	+2.0/-2.0	NON-PLATED	2
V	40.0	+2.0/-2.0	NON-PLATED	4
W	42.0	+2.0/-2.0	NON-PLATED	4
X	43.0	+2.0/-2.0	NON-PLATED	1
Y	47.0	+2.0/-2.0	NON-PLATED	2
Z	51.0	+2.0/-2.0	NON-PLATED	2
AA	63.0	+2.0/-2.0	NON-PLATED	1
*A	78.74	+2.0/-2.0	NON-PLATED	2
AB	89.0	+2.0/-2.0	NON-PLATED	4
AC	92.52	+2.0/-0.0	NON-PLATED	4
AD	125.0	+2.0/-2.0	NON-PLATED	1
AE	127.95	+2.0/-2.0	NON-PLATED	2
AF	138.0	+2.0/-2.0	NON-PLATED	4
=	75.0x28.0	+3.0/-3.0	PLATED	4
=	75.0x38.0	+3.0/-3.0	PLATED	2
=	78.74x44.09	+3.0/-3.0	PLATED	2
=	98.43x39.37	+3.0/-3.0	PLATED	1
=	118.11x39.37	+3.0/-3.0	PLATED	1
=	137.8x39.37	+3.0/-3.0	PLATED	1
=	421.0x67.0	+2.0/-2.0	NON-PLATED	1

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN <input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		eINFOCHIPS LIMITED	
DRAWING TITLE FABRICATION DRAWING TMDXEVM66AK2E		SIZE D	PART NUMBER TMDXEVM66AK2E
DATE 04-11-2014		SCALE 1/1	SHEET 1 OF 1